

TCAN944-Q1 Automotive Fault-Protected CAN FD Transceiver with Standby Mode

1 Features

- AEC-Q100 Qualified for automotive applications
 - Human body model (HBM) ESD protection: $\pm 12\text{KV}$ for CANH and CANL pins as per AEC Q100-002
 - Charged-device model (CDM) ESD protection: $\pm 500\text{V}$ as per AEC Q100-011
 - IEC 61000-4-2 Contact discharge: $\pm 8\text{KV}$ (unpowered)
- Compatible with ISO 11898-2:2024 physical layer standard
- **Functional Safety-Capable**
 - [Documentation available to aid in functional safety system design](#)
- Support of classical CAN and optimized CAN FD performance at 2Mbps and 5Mbps
 - Short and symmetrical propagation delays for enhanced timing margin
- TCAN944V-Q1 I/O voltage range supports 2.9V to 5.25V
- Support for 12V battery applications
- Receiver common mode input voltage: $\pm 12\text{V}$
- Protection features:
 - Bus fault protection: $\pm 40\text{V}$
 - Undervoltage protection
 - TXD-dominant time-out (DTO)
 - Thermal-shutdown protection (TSD)
- Operating modes:
 - Normal mode
 - Low power standby mode supporting remote wake-up request
- Optimized behavior when unpowered
 - Bus and logic pins are high impedance (no load to operating bus or application)
 - Hot-plug capable: power up/down glitch-free operation on bus and RXD output
- 8-Pin SOIC, small footprint SOT-23 and leadless VSON-8 package with improved automated optical inspection (AOI) capability

2 Applications

- Automotive and transportation
 - [Body control modules](#)
 - [Automotive gateway](#)
 - [Advanced driver assistance system \(ADAS\)](#)
 - [Infotainment](#)

3 Description

The TCAN944-Q1 is a high speed controller area network (CAN) transceiver that is compatible with physical layer requirements of the ISO 11898-2:2024 high-speed CAN specification.

The device includes internal logic level translation via the V_{IO} pin to allow for interfacing the transceiver I/O directly to 3.3V, or 5V logic levels. The transceiver supports a low-power standby mode and wake over CAN which is compatible to the ISO 11898-2:2024 defined wake-up pattern (WUP).

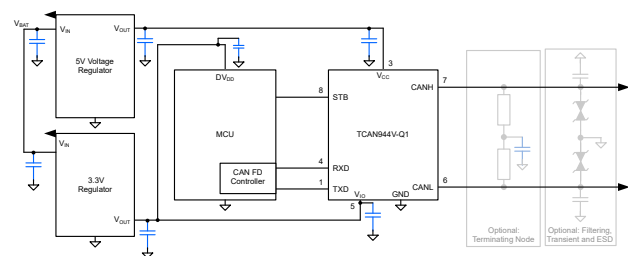
The transceivers also include thermal-shutdown (TSD), TXD-dominant time-out (DTO), supply undervoltage detection, and $\pm 40\text{V}$ bus fault protection. The devices have defined fail-safe behavior in supply undervoltage or floating pin scenarios. These transceivers are not only available in industry-standard SOIC-8 and VSON-8 packages, but also have a space-saving small footprint SOT-23 package option.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾
TCAN944-Q1	SOIC (D)	4.9mm × 6mm
	VSON (DRB)	3mm × 3mm
	SOT-23 (DDF)	2.9mm × 2.8mm

(1) For more information, see [Section 12](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.



Simplified Schematic



Table of Contents

1 Features	1	8.2 Functional Block Diagram.....	14
2 Applications	1	8.3 Feature Description.....	14
3 Description	1	8.4 Device Functional Modes.....	18
4 Device Comparison	2	9 Application Information Disclaimer	21
5 Pin Configuration and Functions	3	9.1 Application Information.....	21
6 Specifications	4	9.2 Typical Application.....	21
6.1 Absolute Maximum Ratings.....	4	9.3 System Examples.....	23
6.2 ESD Ratings	4	9.4 Power Supply Recommendations.....	24
6.3 ESD Ratings, IEC Specification	4	9.5 Layout.....	24
6.4 Recommended Operating Conditions.....	5	10 Device and Documentation Support	26
6.5 Thermal Information.....	5	10.1 Receiving Notification of Documentation Updates.....	26
6.6 Power Supply Characteristics.....	5	10.2 Support Resources.....	26
6.7 Dissipation Ratings.....	6	10.3 Trademarks.....	26
6.8 Electrical Characteristics.....	6	10.4 Electrostatic Discharge Caution.....	26
6.9 Switching Characteristics.....	8	10.5 Glossary.....	26
6.10 Typical Characteristics.....	9	11 Revision History	26
7 Parameter Measurement Information	10	12 Mechanical, Packaging, and Orderable Information	26
8 Detailed Description	13		
8.1 Overview.....	13		

4 Device Comparison

Device Comparison Table

Part Number	Low Voltage I/O Logic Support on Pin 5	Pin 8 Mode Selection
TCAN944-Q1	No	Low Power Standby Mode with Remote Wake
TCAN944V-Q1	Yes	

5 Pin Configuration and Functions

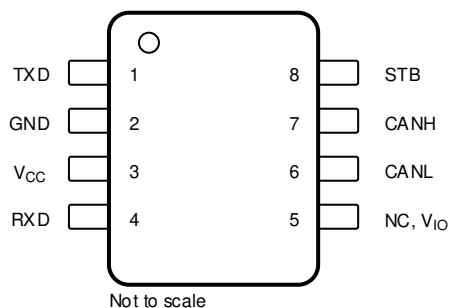


Figure 5-1. DDF Package, 8-Pin SOT (Top View)

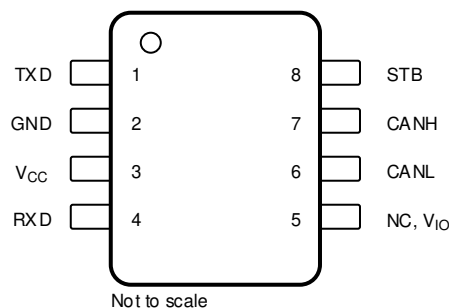


Figure 5-2. D Package, 8-Pin SOIC (Top View)

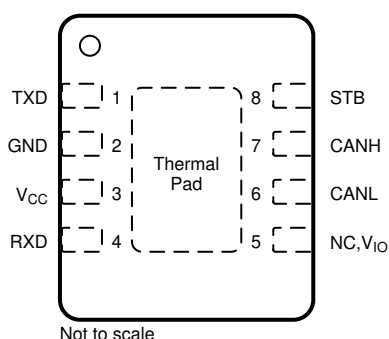


Figure 5-3. DRB Package, 8-Pin VSON (Top View)

Table 5-1. Pin Functions

Pins		Type ⁽¹⁾	Description
Name	No.		
TXD	1	Digital Input	CAN transmit data input; integrated pull-up
GND	2	GND	Ground connection
V _{CC}	3	Supply	5V supply voltage
RXD	4	Digital Output	CAN receive data output, tri-stated when device powered off
NC	5	—	Not internally connected; Devices without V _{IO}
V _{IO}		Supply	I/O supply voltage for devices with suffix 'V'
CANL	6	Bus IO	Low-level CAN bus input/output line
CANH	7	Bus IO	High-level CAN bus input/output line
STB	8	Digital Input	Standby input for mode control; integrated pull-up
Thermal Pad (VSON only)		—	Connect the thermal pad to any internal PCB ground plane using multiple vias for improved thermal performance.

(1) I = input, O = output, I/O = input and output, P = power

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾⁽²⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	−0.3	6	V
V _{IO}	Supply voltage I/O level shifter	−0.3	6	V
V _{BUS}	CAN Bus I/O voltage (CANH, CANL)	−40	40	V
V _{DIFF}	Max differential voltage range between CANH and CANL	−40	40	V
V _{Logic_Input}	Logic input terminal voltage	−0.3	6	V
V _{RXD}	RXD output terminal voltage range	−0.3	6	V
I _{O(RXD)}	RXD output current	−8	8	mA
T _J	Operating virtual junction temperature range	−40	165	°C
T _{STG}	Storage temperature	−65	150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) All voltage values, except differential I/O bus voltages, are with respect to ground terminal.

6.2 ESD Ratings

			VALUE	UNIT
V _{ESD}	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾	±2000	V
		HBM classification level 3A for all pins		
		HBM classification level 3B for global pins CANH & CANL	±12000	V
		Charged-device model (CDM), per AEC Q100-011	±500	V
		CDM classification level C5 for all pins		

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 ESD Ratings, IEC Specification

				VALUE	UNIT
V _{ESD}	System Level Electro-Static Discharge (ESD)	CAN bus terminals (CANH CANL) to GND	IEC 61000-4-2: Powered Contact Discharge	±8000	V
V _{TRAN}	ISO7637 ISO Pulse Transients ⁽¹⁾	CAN bus terminals (CANH, CANL)	Pulse 1	−100	V
			Pulse 2a	75	V
			Pulse 3a	−150	V
			Pulse 3b	100	V
	ISO7637 Slow transients pulse ⁽²⁾	CAN bus terminals (CANH CANL) to GND	Direct coupling capacitor "slow transient pulse" with 100nF coupling capacitor - powered	±30	V

- (1) Tested according to IEC 62228-3 CAN Transceivers (2018), Section 6.3; standard pulses parameters defined in ISO 7637-2 (2011).
- (2) Tested according to ISO 7637-3 (2017); Electrical transient transmission by capacitive and inductive coupling via lines other than supply lines.

6.4 Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.75	5	5.25	V
V _{IO}	Supply voltage for I/O level shifter	2.9		5.25	V
I _{OH} (RXD)	RXD terminal high level output current	–2			mA
I _{OL} (RXD)	RXD terminal low level output current			2	mA
T _J	Operational free-air temperature (see thermal characteristics table)	–40		150	°C
T _{SDR}	Thermal shutdown	160			°C
T _{SDF}	Thermal shutdown release			150	°C
T _{SD} (HYS)	Thermal shutdown hysteresis		10		°C

6.5 Thermal Information

THERMAL METRIC ⁽¹⁾		TCAN944(V)-Q1		UNIT
		D (SOIC)	DRB (VSON)	
R _{θJA}	Junction-to-ambient thermal resistance	123.1	76.9	°C/W
R _{θJC} (top)	Junction-to-case (top) thermal resistance	65.2	74.8	°C/W
R _{θJB}	Junction-to-board thermal resistance	72.5	45.1	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	17.3	7.0	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	72.1	41.2	°C/W
R _{θJC} (bot)	Junction-to-case (bottom) thermal resistance	–	21.2	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

6.6 Power Supply Characteristics

Over recommended operating conditions with T_J = –40°C to 150°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I _{CC}	Supply current normal mode	Dominant	TXD = 0V, R _L = 60Ω, C _L = open		44	70	mA
	Supply current normal mode	Dominant	TXD = 0V, R _L = 50Ω, C _L = open		48	80	mA
	Supply current normal mode	Dominant with bus fault	TXD = 0V, CANH = CANL = ±25V, R _L = open, C _L = open			130	mA
	Supply current normal mode	Recessive	TXD = V _{CC} , R _L = 50Ω, C _L = open, RCM = open		5.6	10	mA
	Supply current standby mode	TCAN944V	TXD = V _{IO} , R _L = 50Ω, C _L = open			5	μA
	Supply current standby mode	TCAN944	TXD = V _{CC} , R _L = 50Ω, C _L = open			30	μA
I _{IO}	I/O supply current normal mode	Dominant	RXD floating, TXD = 0V		135	400	μA
	I/O supply current normal mode	Recessive	RXD floating, TXD = V _{IO}		28	150	μA
	I/O supply current standby mode		RXD floating, TXD = V _{IO}		20	28	μA
UV _{VCC}	Rising under voltage detection on V _{CC} for protected mode				4.2	4.6	V
UV _{VCC}	Falling under voltage detection on V _{CC} for protected mode			3.5	4	4.5	V
UV _{VIO}	Rising under voltage detection on V _{IO}				2.5	2.9	V
UV _{VIO}	Falling under voltage detection on V _{IO}			2.1	2.4		V

Over recommended operating conditions with $T_J = -40^{\circ}\text{C}$ to 150°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
TSD	Thermal shutdown temperature	165	180	195	
TSD_HYS	Thermal shutdown hysteresis		10		

6.7 Dissipation Ratings

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
P_D	Average power dissipation Normal mode	$V_{CC} = 5\text{V}$, $V_{IO} = 3.3\text{V}$, $T_J = 27^{\circ}\text{C}$, $R_L = 60\Omega$, $C_{L_RXD} = 15\text{pF}$ TXD input = 250kHz 50% duty cycle square wave			mW
		$V_{CC} = 5.25\text{V}$, $V_{IO} = 3.3\text{V}$, $T_J = 150^{\circ}\text{C}$, $R_L = 60\Omega$, $C_{L_RXD} = 15\text{pF}$ TXD input = 2.5MHz 50% duty cycle square wave			mW

6.8 Electrical Characteristics

Over recommended operating conditions with $T_J = -40^{\circ}\text{C}$ to 150°C (unless otherwise noted)⁽¹⁾⁽²⁾

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Driver Electrical Characteristics					
$V_{CANH(D)}$	Bus output voltage (dominant) CANH	$V_{TXD} = 0\text{V}$, $R_L = 50\Omega$ to 65Ω , $C_L = \text{open}$, $R_{CM} = \text{open}$	2.75	4.5	V
$V_{CANL(D)}$	Bus output voltage (dominant) CANL	$V_{TXD} = 0\text{V}$, $R_L = 50\Omega$ to 65Ω , $C_L = \text{open}$, $R_{CM} = \text{open}$	0.5	2.25	V
$V_{CANH(R)}$ $V_{CANL(R)}$	Bus output voltage (recessive)	$V_{TXD} = V_{CC}$, $R_L = \text{open}$ (no load), $R_{CM} = \text{open}$	2	3	V
V_{SYM}	Driver symmetry $(V_{O(CANH)} + V_{O(CANL)})/V_{CC}$	STB = 0V, $R_L = 60\Omega$, CSPLIT = 4.7nF, CL = open, $R_{CM} = \text{open}$, TXD = 250KHz, 1MHz, 2.5MHz	0.9	1.1	V/V
V_{SYM_DC}	DC output symmetry $(V_{CC} - V_{O(CANH)} - V_{O(CANL)})$	$R_L = 60\Omega$, $C_L = \text{open}$	-400	400	mV
$V_{DIFF(D)}$	Differential output voltage normal mode Dominant	TXD = 0V, $50\Omega \leq R_L \leq 65\Omega$, $C_L = \text{open}$	1.5	3	V
		TXD = 0V, $45\Omega \leq R_L \leq 70\Omega$, $C_L = \text{open}$	1.4	3.3	V
		TXD = 0V, $R_L = 2240\Omega$, $C_L = \text{open}$	1.5	5	V
$V_{DIFF(R)}$	Differential output voltage normal mode Recessive	TXD = V_{CC} or VIO, $R_L = 60\Omega$, $C_L = \text{open}$	-120	12	mV
		Normal mode, TXD = V_{CC} or VIO, $R_L = \text{open}$, $C_L = \text{open}$	-50	50	mV
$V_{CANH(INACT)}$	Bus output voltage on CANH with bus biasing inactive	$V_{TXD} = V_{CC}$ or VIO, $R_L = \text{open}$, $C_L = \text{open}$, $R_{CM} = \text{open}$	-0.1	0.1	V
$V_{CANL(INACT)}$	Bus output voltage on CANL with bus biasing inactive	$V_{TXD} = V_{CC}$ or VIO, $R_L = \text{open}$, $C_L = \text{open}$, $R_{CM} = \text{open}$	-0.1	0.1	V
$V_{DIFF(INACT)}$	Bus output voltage on CANH - CANL (recessive) with bus biasing inactive	$V_{TXD} = V_{CC}$ or VIO, $R_L = \text{open}$, $C_L = \text{open}$, $R_{CM} = \text{open}$	-0.2	0.2	V
$I_{CANH(OS)}$	Short-circuit steady-state output current, Dominant	$-3.0\text{V} \leq V_{CANH} \leq +18.0\text{V}$, CANL = open, $V_{TXD} = 0\text{V}$	-115		mA
$I_{CANL(OS)}$		$-3.0\text{V} \leq V_{CANL} \leq +18.0\text{V}$, CANH = open, $V_{TXD} = 0\text{V}$		115	mA
I_{OS_REC}	Short-circuit steady-state output current; Recessive	$-40\text{V} \leq V_{BUS} \leq +40\text{V}$, $V_{BUS} = \text{CANH} = \text{CANL}$	-5	5	mA
Receiver Electrical Characteristics					
$V_{DIFF_RX(D)}$	Receiver dominant state differential input voltage range, bus biasing active	$-12\text{V} \leq V_{CANL} \leq +12\text{V}$ $-12\text{V} \leq V_{CANH} \leq +12\text{V}$	0.9	8	V
$V_{DIFF_RX(R)}$	Receiver recessive state differential input voltage range, bus biasing active	$-12\text{V} \leq V_{CANL} \leq +12\text{V}$ $-12\text{V} \leq V_{CANH} \leq +12\text{V}$	-3	0.5	V

Over recommended operating conditions with TJ = -40°C to 150°C (unless otherwise noted)⁽¹⁾⁽²⁾

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{HYS}	Hysteresis voltage for input-threshold, normal and selective wake modes	-12V ≤ V _{CM} ≤ 12V		80		mV
V _{DIFF_RX(D_INA CT)}	Receiver dominant state differential input voltage range, bus biasing in-active	-12V ≤ V _{CANL} ≤ +12V -12V ≤ V _{CANH} ≤ +12V	1.15		8	V
V _{DIFF_RX(R_INA CT)}	Receiver recessive state differential input voltage range, bus biasing in-active	-12V ≤ V _{CANL} ≤ +12V -12V ≤ V _{CANH} ≤ +12V	-3		0.4	V
V _{CM}	Common mode range:		-12		12	V
I _{LKG(IOFF)}	Power-off (unpowered) bus input leakage current	CANH = CANL = 5V, V _{CC} = V _{IO} = GND			5	μA
C _I powered Normal	Input capacitance to ground (CANH or CANL)	TXD = V _{CC} , V _{IO} = V _{CC}			20	pF
C _{ID} powered Normal	Differential input capacitance	TXD = V _{CC} , V _{IO} = V _{CC}			10	pF
R _{DIFF}	Differential input resistance during passive recessive state	V _{TXD} = V _{CC} or V _{IO} , normal mode: -2.0V ≤ V _{CANH} ≤ +7.0V; -2.0V ≤ V _{CANL} ≤ +7.0V	18		90	kΩ
R _{SE_CANH} R _{SE_CANL}	Single ended Input resistance during passive recessive state	-2V ≤ V _{CANH} ≤ +7V -2V ≤ V _{CANL} ≤ +7V	9		45	kΩ
m _R	Input resistance matching: $[1 - (R_{IN(CANH)} / R_{IN(CANL)})] \times 100\%$	V _{CANH} = V _{CANL} = 5V	-2%		2%	
TXD Terminal (CAN Transmit Data Input)						
V _{IH}	High-level input voltage	TCAN944	0.7 × V _{CC}			V
V _{IH}	High-level input voltage	TCAN944V	0.7 × V _{IO}			V
V _{IL}	Low-level input voltage	TCAN944			0.3 × V _{CC}	V
V _{IL}	Low-level input voltage	TCAN944V			0.3 × V _{IO}	V
I _{IH}	High-level input leakage current	TXD = V _{CC} = V _{IO} = 5.25V	-2.5	0	1	μA
I _{IL}	Low-level input leakage current	TXD = 0V, V _{CC} = V _{IO} = 5.25V	-200		-20	μA
I _{LKG(OFF)}	Unpowered leakage current	TXD = 5.25V, V _{CC} = V _{IO} = 0V	-1	0	1	μA
C _I	Input Capacitance	V _{IN} = 0.4×sin(2×π×2×10 ⁶ ×t)+2.5V		2		pF
RXD Terminal (CAN Receive Data Output)						
V _{OH}	High-level input voltage	I _O = -2mA, TCAN944	0.8 × V _{CC}			V
V _{OH}	High-level input voltage	I _O = -2mA, TCAN944V	0.8 × V _{IO}			V
V _{OL}	Low-level input voltage	I _O = 2mA, TCAN944			0.2 × V _{CC}	V
V _{OL}	Low-level input voltage	I _O = 2mA, TCAN944V			0.2 × V _{IO}	V
I _{LKG(OFF)}	Unpowered leakage current	RXD = 5.25V, V _{CC} = V _{IO} = 0V	-1	0	1	μA
STB Terminal						
V _{IH}	High-level input voltage	TCAN944	0.7 × V _{CC}			V
V _{IH}	High-level input voltage	TCAN944V	0.7 × V _{IO}			V
V _{IL}	Low-level input voltage	TCAN944			0.3 × V _{CC}	V
V _{IL}	Low-level input voltage	TCAN944V			0.3 × V _{IO}	V
I _{IH}	High-level input leakage current STB	V _{CC} = V _{IO} = STB = 5.25V	-2		2	μA
I _{IL}	Low-level input leakage current STB	V _{CC} = V _{IO} = 5.25V, STB = 0V	-20		-2	μA
I _{LKG(OFF)}	Unpowered leakage current	STB = 5.25V, V _{CC} = V _{IO} = 0V	-1	0	1	μA

- (1) All typical values are at 25°C and supply voltages of V_{CC} = 5V. R_L = 60Ω over operating free-air temperature range (unless otherwise noted)
- (2) For the bus output voltage (recessive) will be the same if the device is in normal mode with STB terminal LOW or if the device is in standby mode with the STB terminal is HIGH.

6.9 Switching Characteristics

Over recommended operating conditions with $T_J = -40^{\circ}\text{C}$ to 150°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Device Switching Characteristics						
t _{PROP(LOOP1)}	Total loop delay, driver input (TXD) to receiver output (RXD), recessive to dominant	Normal mode, V _{IO} = 3V to 5V, R _L = 60Ω, C _L = 100pF, C _{L_RXD} = 15pF		100	220	ns
t _{PROP(LOOP2)}	Total loop delay, driver input (TXD) to receiver output (RXD), dominant to recessive	Normal mode, V _{IO} = 3V to 5V, R _L = 60Ω, C _L = 100pF, C _{L_RXD} = 15pF		110	220	ns
t _{MODE}	Mode change time, from Normal to Standby or from Standby to Normal				45	μs
t _{WK_FILTER}	Filter time for a valid wake-up pattern		0.5		1.8	μs
t _{WK_TIMEOUT}	Bus wake-up timeout value		0.8		6	ms
Driver Switching Characteristics						
t _{pHR}	Propagation delay time, high TXD to driver recessive (dominant to recessive)	R _L = 60Ω, C _L = 100pF, R _{CM} = open		50		ns
t _{pLD}	Propagation delay time, low TXD to driver dominant (recessive to dominant)			45		ns
t _{sk(p)}	Pulse skew (t _{pHR} - t _{pLD})			4		ns
t _R	Differential output signal rise time			32		ns
t _F	Differential output signal fall time			27		ns
t _{TXD_DTO}	Dominant timeout	R _L = 60Ω, C _L = 100pF	0.8		6.5	ms
Receiver Switching Characteristics						
t _{pRH}	Propagation delay time, bus recessive input to high output (dominant to recessive)	C _{L_RXD} = 15pF		75		ns
t _{pDL}	Propagation delay time, bus dominant input to low output (recessive to dominant)			70		ns
t _R	RXD output signal rise time			10		ns
t _F	RXD output signal fall time			10		ns
FD Timing Characteristics						
t _{ΔBit(Bus)}	Transmitted recessive bit width variation: t _{BIT(TXD)} = 500ns	R _L = 60Ω, C _L = 100pF, C _{L_RXD} = 15pF t _{ΔBit(Bus)} = t _{BIT(Bus)} - t _{BIT(TXD)}	-65		30	ns
t _{ΔBit(Bus)}	Transmitted recessive bit width variation: t _{BIT(TXD)} = 200ns	R _L = 60Ω, C _L = 100pF, C _{L_RXD} = 15pF t _{ΔBit(Bus)} = t _{BIT(Bus)} - t _{BIT(TXD)}	-45		10	ns
t _{ΔBit(RXD)}	Received recessive bit width variation: t _{BIT(TXD)} = 500ns	R _L = 60Ω, C _L = 100pF, C _{L_RXD} = 15pF t _{ΔBit(RXD)} = t _{BIT(RXD)} - t _{BIT(TXD)}	-100		50	ns
t _{ΔBit(RXD)}	Received recessive bit width variation: t _{BIT(TXD)} = 200ns	R _L = 60Ω, C _L = 100pF, C _{L_RXD} = 15pF t _{ΔBit(RXD)} = t _{BIT(RXD)} - t _{BIT(TXD)}	-80		20	ns
t _{ΔREC}	Receiver timing symmetry with t _{BIT(TXD)} = 500ns	R _L = 60Ω, C _L = 100pF, C _{L_RXD} = 15pF	-65		40	ns
t _{ΔREC}	Receiver timing symmetry with t _{BIT(TXD)} = 200ns	Δt _{REC} = t _{BIT(RXD)} - t _{BIT(BUS)}	-45		15	ns

6.10 Typical Characteristics

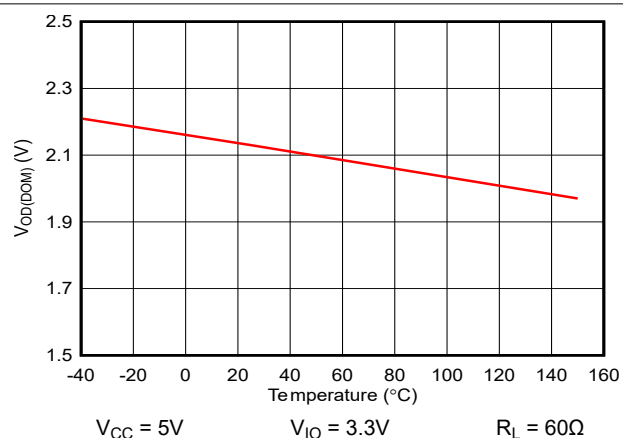


Figure 6-1. $V_{OD(DOM)}$ vs Temperature

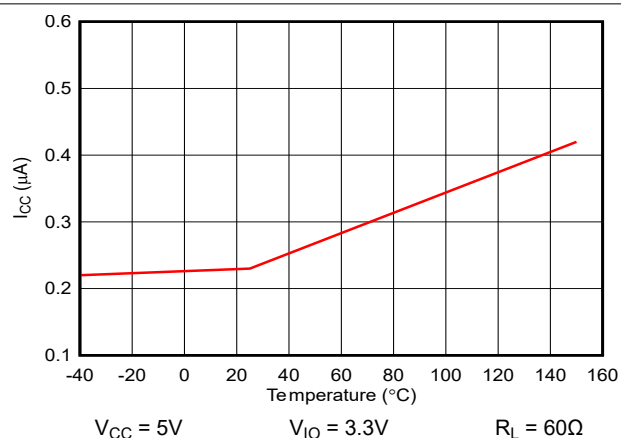


Figure 6-2. I_{CC} Silent vs Temperature

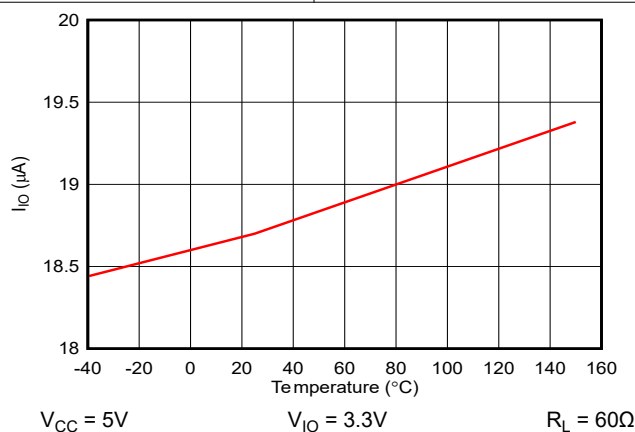


Figure 6-3. I_{IO} Silent vs Temperature

7 Parameter Measurement Information

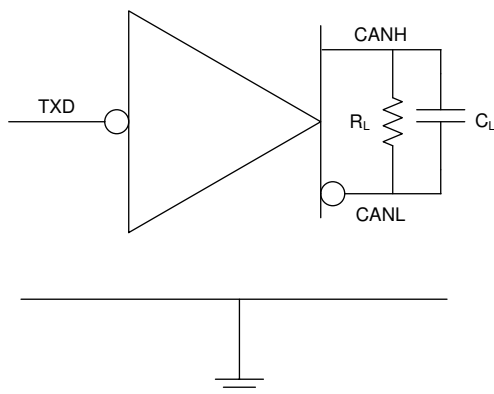


Figure 7-1. I_{CC} Test Circuit

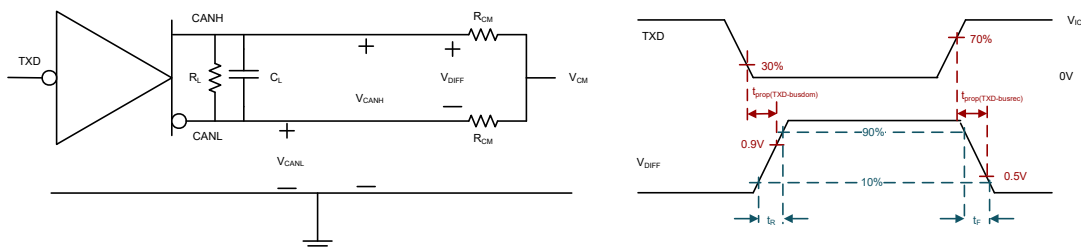


Figure 7-2. Driver Test Circuit and Measurement

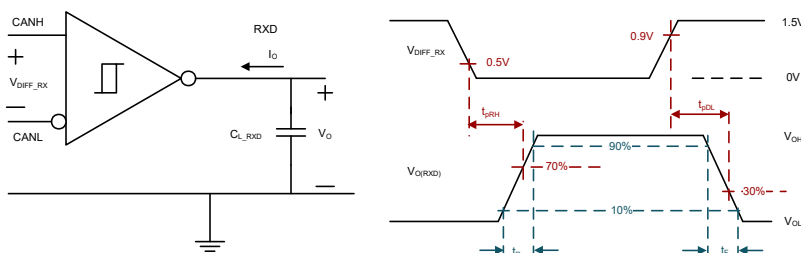


Figure 7-3. Receiver Test Circuit and Measurement

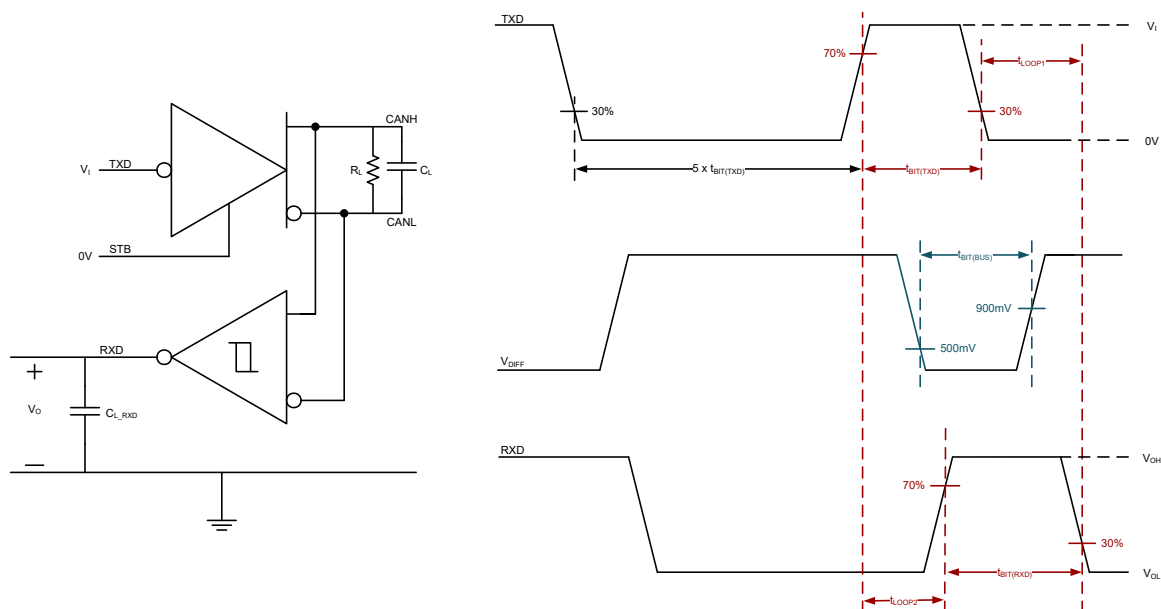


Figure 7-4. Transmitter and Receiver Timing Test Circuit and Measurement

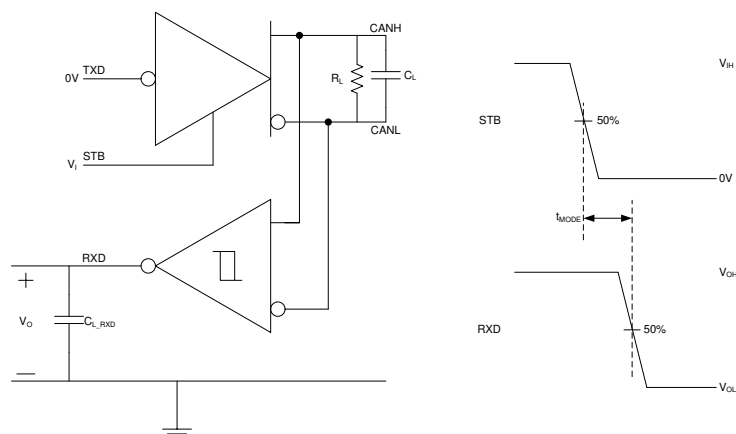


Figure 7-5. t_{MODE} Test Circuit and Measurement

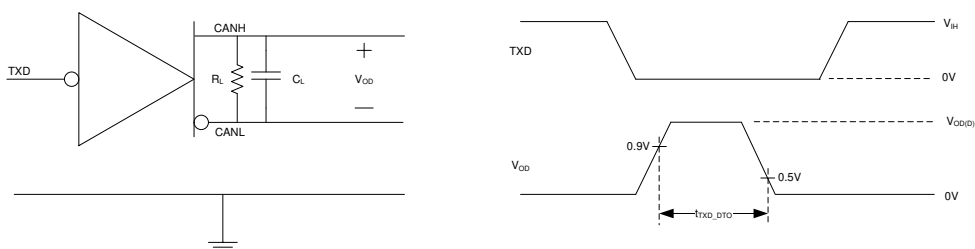


Figure 7-6. TXD Dominant Timeout Test Circuit and Measurement

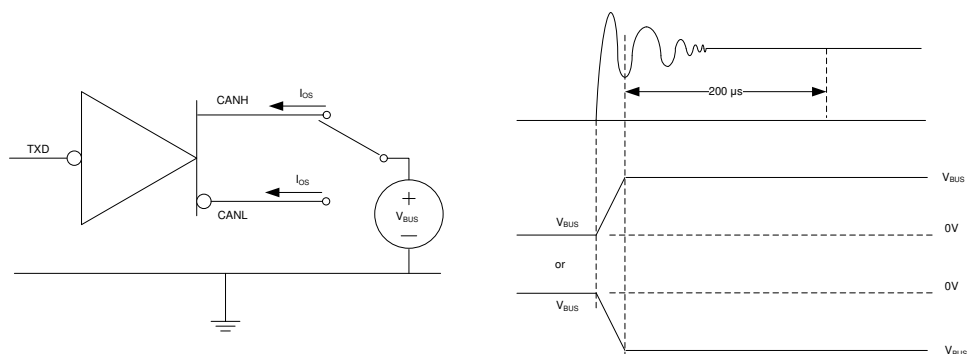


Figure 7-7. Driver Short-Circuit Current Test and Measurement

8 Detailed Description

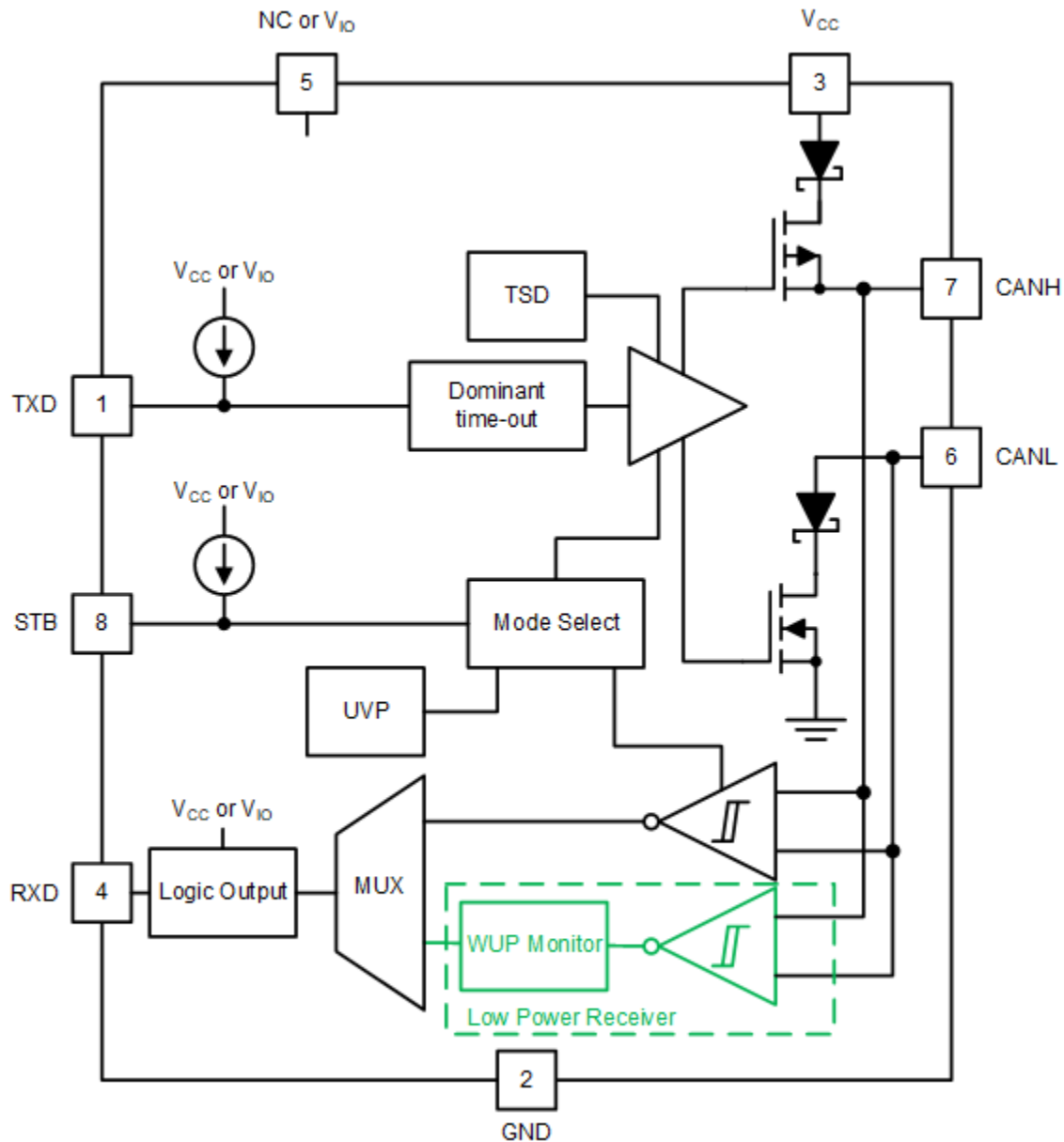
8.1 Overview

The device is compatible with the specifications of the ISO 11898-2:2024 high-speed CAN (Controller Area Network) physical layer standard. The transceivers provide several different protection features for the stringent automotive system requirements while also supporting CAN FD data rates up to 5Mbps.

The device supports the following CAN and CAN FD standards:

- Physical layer compatibility:
 - ISO 11898-2:2024 High speed medium access unit
 - SAE J2284-1: High Speed CAN (HSC) for Vehicle Applications at 125kbps
 - SAE J2284-2: High Speed CAN (HSC) for Vehicle Applications at 250kbps
 - SAE J2284-3: High Speed CAN (HSC) for Vehicle Applications at 500kbps
 - SAE J2284-4: High-Speed CAN (HSC) for Vehicle Applications at 500kbps with CAN FD Data at 2Mbps
 - SAE J2284-5: High-Speed CAN (HSC) for Vehicle Applications at 500kbps with CAN FD Data at 5Mbps

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Pin Description

8.3.1.1 TXD

The TXD input is a logic-level signal, referenced to either V_{CC} or V_{IO} from a CAN controller to the transceiver.

8.3.1.2 GND

GND is the ground pin of the transceiver. The pin must be connected to the PCB ground.

8.3.1.3 V_{CC}

V_{CC} provides the 5V power supply to the CAN transceiver.

8.3.1.4 RXD

RXD is the logic-level signal, referenced to either V_{CC} or V_{IO} , from the TCAN944-Q1 to a CAN controller. This pin is only driven once V_{IO} is present.

8.3.1.5 V_{IO}

The V_{IO} pin provides the digital I/O voltage to match the CAN controller voltage which avoids the requirement for a level shifter. V_{IO} supports voltages from 2.9V to 5.25V providing the widest range of controller support.

8.3.1.6 CANH and CANL

The CANH and CANL pins are the CAN high and CAN low differential bus pins. These pins are internally connected to the CAN transmitter, receiver and the low-power wake-up receiver.

8.3.1.7 STB (Standby)

The STB pin is an input pin used for mode control of the transceiver. The STB pin can be supplied from either the system processor or from a static system voltage source. If normal mode is the only intended mode of operation, the STB pin can be tied directly to GND.

8.3.2 CAN Bus States

The CAN bus has two logical states during operation, recessive and dominant. See [Figure 8-1](#) and [Figure 8-2](#).

A dominant bus state occurs when the bus is driven differentially and corresponds to a logic low on the TXD and RXD pins. A recessive bus state occurs when the bus is biased to $V_{CC}/2$ via the high-resistance internal input resistors (R_{IN}) of the receiver and corresponds to a logic high on the TXD and RXD pins.

A dominant state overwrites the recessive state during arbitration. Multiple CAN nodes may be transmitting a dominant bit at the same time during arbitration, and in this case, the differential voltage of the bus is greater than the differential voltage of a single driver.

The TCAN944(V)-Q1 transceiver implements a low-power standby (STB) mode which enables a third bus state where the bus pins are weakly biased to ground via the high resistance internal resistors of the receiver. See [Figure 8-1](#) and [Figure 8-2](#).

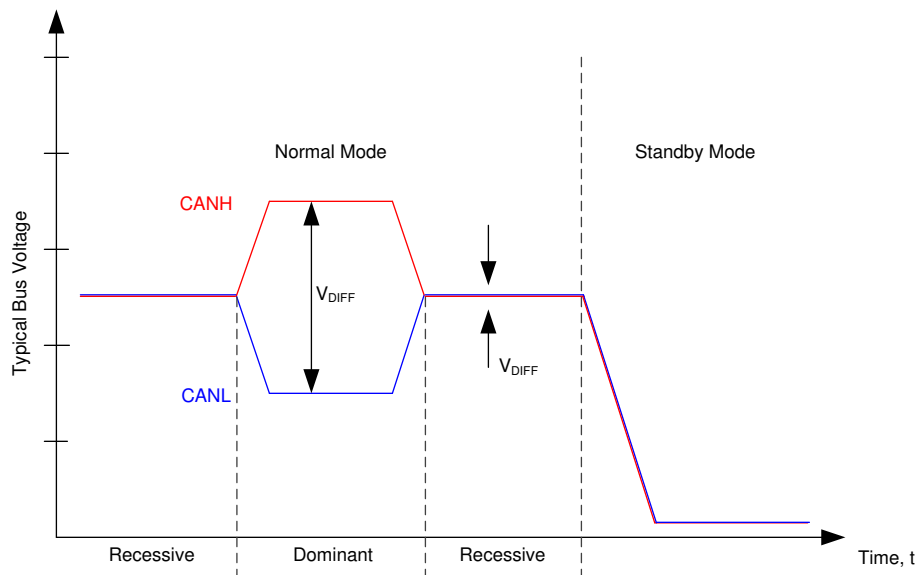
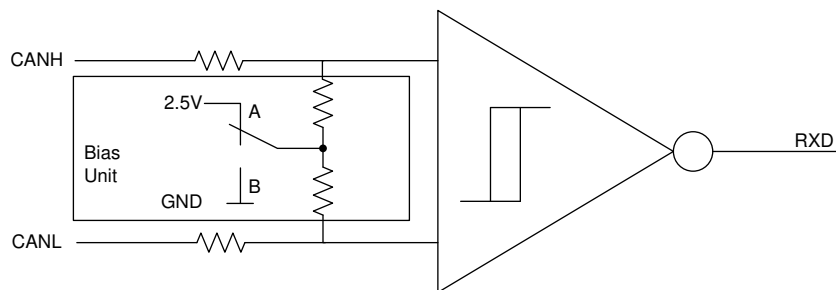


Figure 8-1. Bus States



A - Normal Mode B - Standby Mode

Figure 8-2. Simplified Recessive Common Mode Bias Unit and Receiver

8.3.3 TXD Dominant Timeout (DTO)

During normal mode, the only mode where the CAN driver is active, the TXD DTO circuit prevents the local node from blocking network communication in the event of a hardware or software failure where TXD is held dominant longer than the timeout period t_{TXD_DTO} . The TXD DTO circuit is triggered by a falling edge on TXD. If no rising edge is seen before the timeout period of the circuit, t_{TXD_DTO} , the CAN driver is disabled. This frees the bus for communication between other nodes on the network. The CAN driver is reactivated when a recessive signal is seen on the TXD pin; thus, clearing the dominant time out. The receiver remains active and biased to $V_{CC}/2$ and the RXD output reflects the activity on the CAN bus during the TXD DTO fault.

The minimum dominant TXD time allowed by the TXD DTO circuit limits the minimum possible transmitted data rate of the device. The CAN protocol allows a maximum of eleven successive dominant bits (on TXD) for the worst case, where five successive dominant bits are followed immediately by an error frame. The minimum transmitted data rate can be calculated using Equation 1.

$$\text{Minimum Data Rate} = 11\text{bits} / t_{TXD_DTO} = 11\text{bits} / 0.8\text{ms} = 13.75\text{kbps} \quad (1)$$

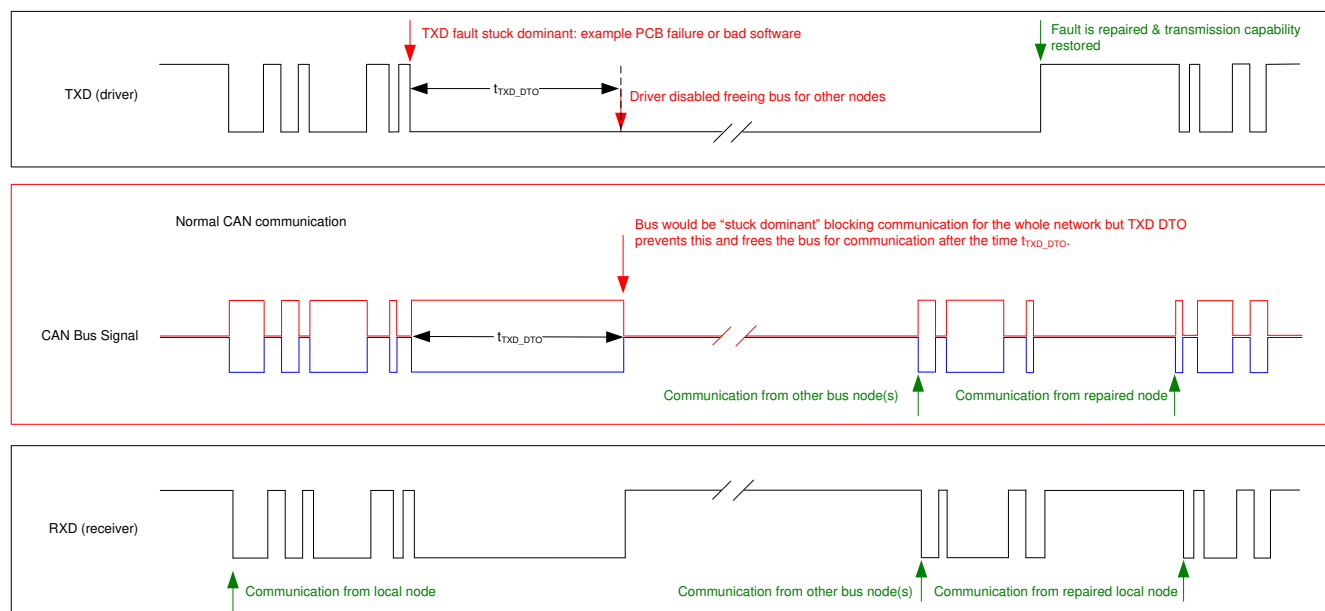


Figure 8-3. Example Timing Diagram for TXD Dominant Timeout

8.3.4 CAN Bus Short-Circuit Current Limiting

The TCAN944(V)-Q1 has several protection features that limit the short-circuit current when a CAN bus line is shorted. These include CAN driver current limiting in the dominant and recessive states and TXD dominant state

timeout. Which prevents permanently having the higher short-circuit current of a dominant state in a system fault. During CAN communication, the bus switches between the dominant and recessive states. The short-circuit current may be viewed as either the current during each bus state or as a DC average current. When selecting termination resistors or a common-mode choke for the CAN design, the average power rating, $I_{OS(AVG)}$, are used. The percentage dominant is limited by the TXD DTO and the CAN protocol. Which has forced state changes and recessive bits due to bit stuffing, control fields, and interframe space. Providing a minimum amount of recessive time on the bus even if the data field contains a high percentage of dominant bits.

The average short-circuit current of the bus depends on the ratio of recessive to dominant bits and their respective short-circuit currents. The average short-circuit current may be calculated using [Equation 2](#).

$$I_{OS(AVG)} = \% \text{ Transmit} \times [(\% \text{ REC_Bits} \times I_{OS(SS_REC)}) + (\% \text{ DOM_Bits} \times I_{OS(SS_DOM)})] + [\% \text{ Receive} \times I_{OS(SS_REC)}] \quad (2)$$

Where:

- $I_{OS(AVG)}$ is the average short-circuit current
- % Transmit is the percentage the node is transmitting CAN messages
- % Receive is the percentage the node is receiving CAN messages
- % REC_Bits is the percentage of recessive bits in the transmitted CAN messages
- % DOM_Bits is the percentage of dominant bits in the transmitted CAN messages
- $I_{OS(SS_REC)}$ is the recessive steady state short-circuit current
- $I_{OS(SS_DOM)}$ is the dominant steady state short-circuit current

This short circuit current and the possible fault cases of the network are taken into consideration when sizing the power supply used to generate the transceivers V_{CC} supply.

8.3.5 Thermal Shutdown (TSD)

If the junction temperature of the TCAN944(V)-Q1 exceeds the thermal shutdown threshold, T_{TSD} , the device turns off the CAN driver circuitry and blocks the TXD to bus transmission path. The shutdown condition is cleared when the junction temperature of the device drops below T_{TSD} . The CAN bus pins are biased to $V_{CC}/2$ during a TSD fault and the receiver to RXD path remains operational. The TCAN944(V)-Q1 TSD circuit includes hysteresis which prevents the CAN driver output from oscillating during a TSD fault.

8.3.6 Undervoltage Lockout

The supply pins, V_{CC} and V_{IO} , have undervoltage detection that places the device into a protected state. This protects the bus during an undervoltage event on either supply pin.

Table 8-1. Undervoltage Lockout - TCAN944-Q1

V_{CC}	DEVICE STATE	BUS	RXD PIN
$> UV_{VCC}$	Normal	Per TXD	Mirrors bus
$< UV_{VCC}$	Protected	High impedance	High impedance

Table 8-2. Undervoltage Lockout - TCAN944V-Q1

V_{CC}	V_{IO}	DEVICE STATE	BUS	RXD PIN
$> UV_{VCC}$	$> UV_{VIO}$	Normal	Per TXD	Mirrors bus
$< UV_{VCC}$	$> UV_{VIO}$	STB = High: Standby Mode	Weakly biased to GND	V_{IO} : Remote wake request See Remote Wake Request via Wake-Up Pattern (WUP) in Standby Mode
		STB = Low: Protected Mode		Recessive
$> UV_{VCC}$	$< UV_{VIO}$	Protected	High impedance	High impedance
$< UV_{VCC}$	$< UV_{VIO}$			

Once the undervoltage condition is cleared and t_{MODE} has expired, the TCAN944-Q1 transitions to normal mode. The host controller can again send and receive CAN traffic.

8.3.7 Unpowered Device

The TCAN944(V)-Q1 is designed to be a passive or no load to the CAN bus if the device is unpowered. The bus pins were designed to have low leakage currents when the device is unpowered, so the device does not load the bus. This is critical if some nodes of the network are unpowered while the rest of the of network remains operational.

The logic pins also have low leakage currents when the device is unpowered, so the pins do not load other circuits which may remain powered.

8.3.8 Floating pins

The device has internal pull-ups on critical pins which place the device into known states if the pin floats. This internal bias cannot be relied upon by design though, especially in noisy environments. Instead internal bias must be considered a failsafe protection feature.

When a CAN controller supporting open-drain outputs is used an adequate external pull-up resistor must be chosen. This makes sure the TXD output of the CAN controller maintains acceptable bit time to the input of the CAN transceiver. See [Table 8-3](#) for details on pin bias conditions.

Table 8-3. Pin Bias

Pin	Pull-up or Pull-down	Comment
TXD	Pull-up	Weakly biases TXD towards recessive to prevent bus blockage or TXD DTO triggering
STB	Pull-up	Weakly biases STB towards low-power standby mode to prevent excessive system power

8.4 Device Functional Modes

8.4.1 Operating Modes

The TCAN944(V)-Q1 has two main operating modes, normal mode and standby mode. Operating mode selection is made by applying a high or low level to the STB pin.

Table 8-4. Operating Modes

STB	Device Mode	Driver	Receiver	RXD Pin
High	Low current standby mode with bus wake-up	Disabled	Low-power receiver and bus monitor enable	High (recessive) until valid WUP is received See Remote Wake Request via Wake-Up Pattern (WUP) in Standby Mode
Low	Normal Mode	Enabled	Enabled	Mirrors bus state

8.4.2 Normal Mode

This is the normal operating mode of the TCAN944(V)-Q1. The CAN driver and receiver are fully operational and CAN communication is bi-directional.

The driver is translating a digital input on the TXD input to a differential output on the CANH and CANL bus pins.

The receiver is translating the differential signal from CANH and CANL to a digital output on the RXD output.

8.4.3 Standby Mode

This is the low-power mode of the TCAN944(V)-Q1. The CAN driver and main receiver are switched off and bi-directional CAN communication is not possible. The low-power receiver and bus monitor circuits are enabled to allow for RXD wake-up requests via the CAN bus. A wake-up request is output to RXD as shown in [Figure 8-4](#). The local CAN protocol controller should monitor RXD for transitions (high-to-low) and reactivate the device to normal mode by pulling the STB pin low. The CAN bus pins are weakly pulled to GND in this mode; see [Figure 8-1](#) and [Figure 8-2](#).

In standby mode, only the V_{IO} supply is required; therefore, the V_{CC} may be switched off for additional system level current savings.

8.4.3.1 Remote Wake Request via Wake-Up Pattern (WUP) in Standby Mode

The TCAN944(V)-Q1 supports a remote wake-up request that is used to indicate to the host controller that the bus is active and the node needs to return to normal operation.

The device uses the multiple filtered dominant wake-up pattern (WUP) from the ISO 11898-2:2024 standard to qualify bus activity. Once a valid WUP has been received, the wake request is indicated to the controller by a falling edge and low period corresponding to a filtered dominant on the RXD output of the TCAN944(V)-Q1.

The WUP consists of a filtered dominant pulse, followed by a filtered recessive pulse, and finally by a second filtered dominant pulse. The first filtered dominant initiates the WUP, and the bus monitor then waits on a filtered recessive; other bus traffic does not reset the bus monitor. Once a filtered recessive is received the bus monitor is waiting for a filtered dominant and again, other bus traffic does not reset the bus monitor. Immediately upon reception of the second filtered dominant the bus monitor recognizes the WUP and drives the RXD output low every time an additional filtered dominant signal is received from the bus.

For a dominant or recessive to be considered filtered, the bus must be in that state for more than the t_{WK_FILTER} time. Due to variability in t_{WK_FILTER} the following scenarios are applicable. Bus state times less than $t_{WK_FILTER(MIN)}$ are never detected as part of a WUP; thus, no wake request is generated. Bus state times between $t_{WK_FILTER(MIN)}$ and $t_{WK_FILTER(MAX)}$ can be detected as part of a WUP and a wake-up request can be generated. Bus state times greater than $t_{WK_FILTER(MAX)}$ are always detected as part of a WUP; thus, a wake request is always generated. See Figure 8-4 for the timing diagram of the wake-up pattern.

The pattern and t_{WK_FILTER} time used for the WUP prevents noise and bus stuck dominant faults from causing false wake-up requests while allowing any valid message to initiate a wake-up request.

The ISO 11898-2:2024 standard has defined times for a short and long wake-up filter time. The t_{WK_FILTER} timing for the device has been picked to be within the minimum and maximum values of both filter ranges. This timing has been chosen such that a single bit time at 500kbps, or two back-to-back bit times at 1Mbps triggers the filter in either bus state. Any CAN frame at 500kbps or less can contain a valid WUP.

For an additional layer of robustness and to prevent false wake-ups, the device implements a wake-up timeout feature. For a remote wake-up event to successfully occur, the entire WUP must be received within the timeout value $t \leq t_{WK_TIMEOUT}$. If not, the internal logic is reset and the transceiver remains in the current state without waking up. The full pattern must then be transmitted again, conforming to the constraints mentioned in this section. See Figure 8-4 for the timing diagram of the wake-up pattern with wake timeout feature.

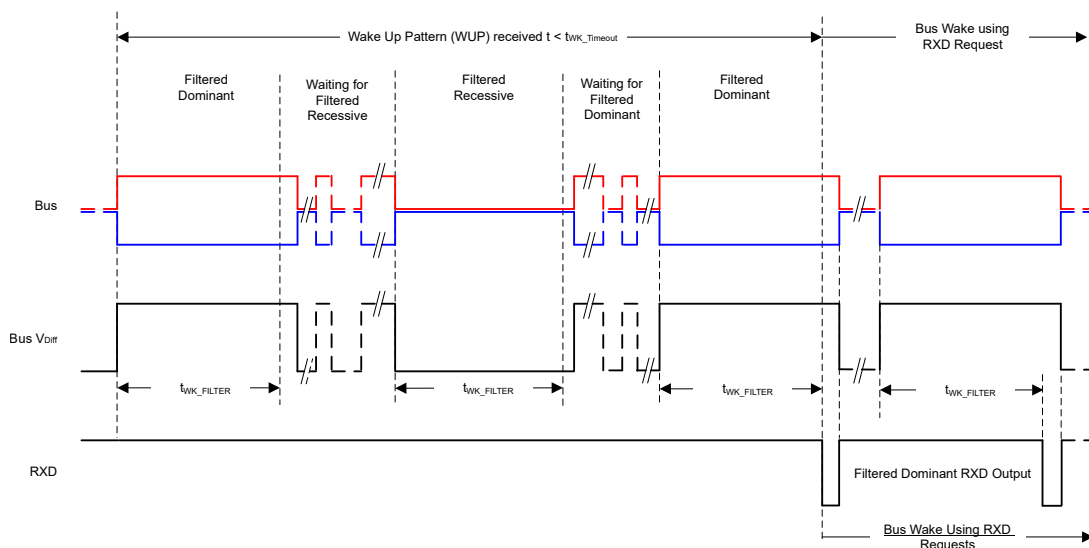


Figure 8-4. Wake-Up Pattern (WUP) with $t_{WK_TIMEOUT}$

8.4.4 Driver and Receiver Function

The TCAN944-Q1 logic I/Os support CMOS levels with respect to either V_{CC} for 5V systems (TCAN944-Q1) or V_{IO} for compatibility with MCUs that support 3.3V or 5V systems (TCAN944V-Q1).

Table 8-5. Driver Function Table

Device Mode	TXD Input ⁽¹⁾	Bus Outputs		Driven Bus State ⁽²⁾
		CANH	CANL	
Normal	Low	High	Low	Dominant
	High or open	High impedance	High impedance	Biased recessive
Standby	X	High impedance	High impedance	Biased to ground

(1) X = irrelevant

(2) For bus state and bias see [Figure 8-1](#) and [Figure 8-2](#)

Table 8-6. Receiver Function Table Normal and Standby Mode

Device Mode	CAN Differential Inputs $V_{ID} = V_{CANH} - V_{CANL}$	Bus State	RXD Pin
Normal	$V_{ID} \geq 0.9V$	Dominant	Low
	$0.5V < V_{ID} < 0.9V$	Undefined	Undefined
	$V_{ID} \leq 0.5V$	Recessive	High
Standby	$V_{ID} \geq 1.15V$	Dominant	High Low if a remote wake event occurred See Figure 8-4
	$0.4V < V_{ID} < 1.15V$	Undefined	
	$V_{ID} \leq 0.4V$	Recessive	
Any	Open ($V_{ID} \approx 0V$)	Open	High

9 Application Information Disclaimer

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

The TCAN944(V)-Q1 transceiver can be used in applications with a host controller or FPGA that includes the link layer portion of the CAN protocol. [Figure 9-1](#) shows a typical configuration for 5V controller applications. The bus termination is shown for illustrative purposes.

9.2 Typical Application

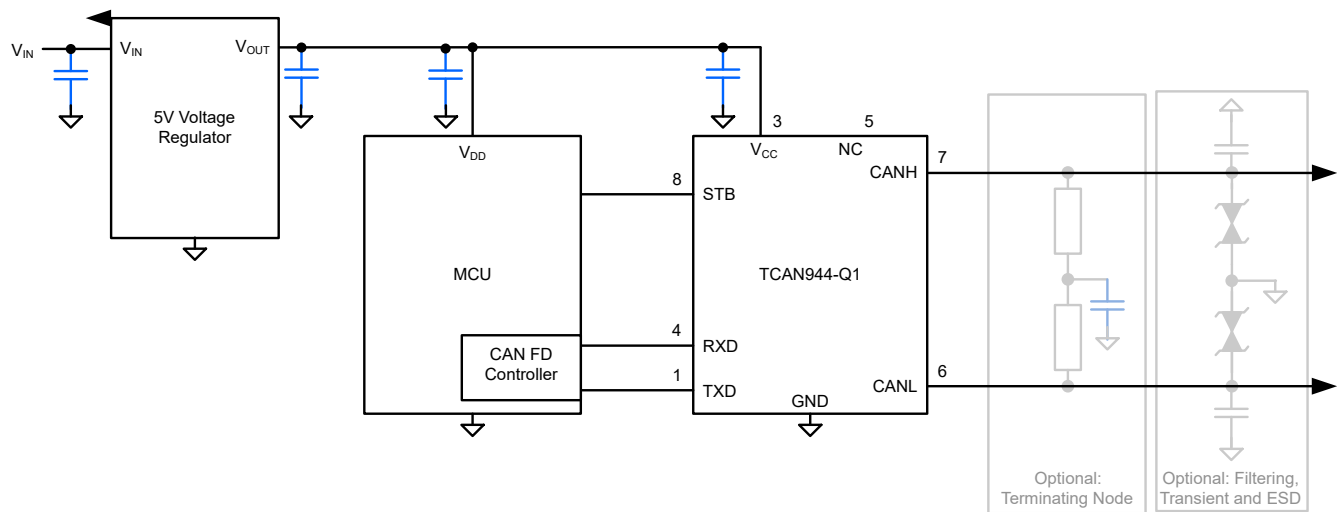


Figure 9-1. Transceiver Application Using 5V IO Connections

9.2.1 Design Requirements

9.2.1.1 CAN Termination

Termination can be a single 120Ω resistor at each end of the bus, either on the cable or in a terminating node. If filtering and stabilization of the common-mode voltage of the bus is desired, then split termination can be used, see [Figure 9-2](#). Split termination improves the electromagnetic emissions behavior of the network by filtering higher-frequency common-mode noise that can be present on the differential signal lines.

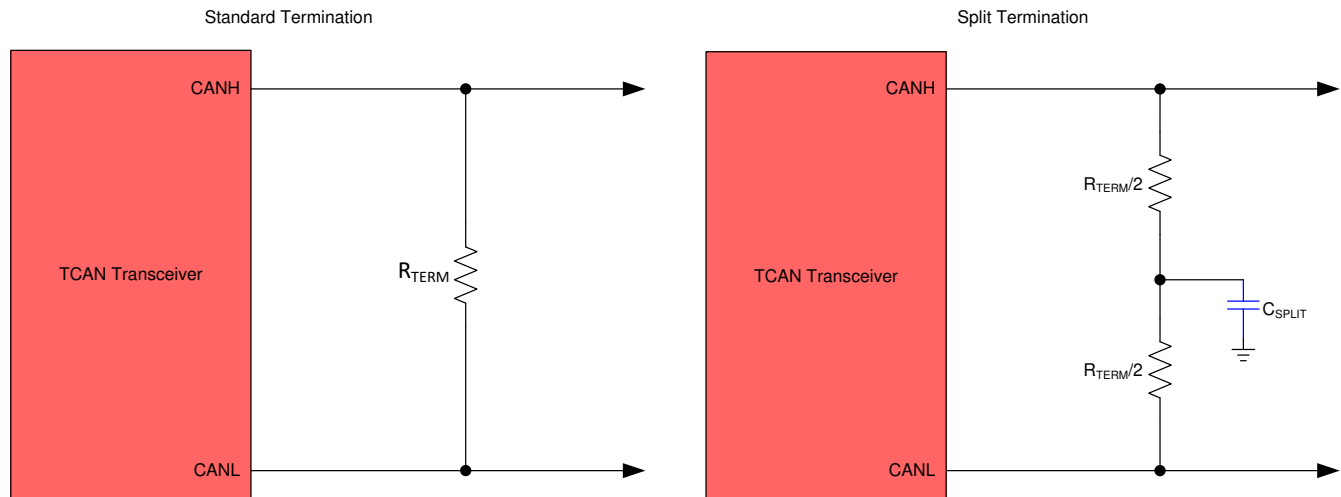


Figure 9-2. CAN Bus Termination Concepts

9.2.2 Detailed Design Procedures

9.2.2.1 Bus Loading, Length and Number of Nodes

A typical CAN application can have a maximum bus length of 40 meters and maximum stub length of 0.3m. However, with careful design, users can have longer cables, longer stub lengths, and many more nodes to a bus. A high number of nodes requires a transceiver with high input impedance such as the TCAN944V-Q1.

Many CAN organizations and standards have scaled the use of CAN for applications outside the original ISO 11898-2 standard. Various CAN standards made system level trade off decisions for data rate, cable length, and parasitic loading of the bus. Examples of these CAN systems level specifications are ARINC 825, CANopen, DeviceNet, SAE J2284, SAE J1939, and NMEA 2000.

A CAN network system design is a series of tradeoffs. In the ISO 11898-2:2024 specification the driver differential output is specified with a bus load that can range from 50Ω to 65Ω where the differential output must be greater than 1.5V. The TCAN944(V)-Q1 family is specified to meet the 1.5V requirement down to 50Ω and is specified to meet 1.4V differential output at 45Ω bus load. The differential input resistance of the device is a minimum of 18kΩ. If 50 TCAN944V-Q1 transceivers are in parallel on a bus, this is equivalent to a 360Ω differential load in parallel with the nominal 60Ω bus termination which gives a total bus load of approximately 51Ω. Therefore, the TCAN944(V)-Q1 family theoretically supports over 50 transceivers on a single bus segment. For a CAN network design margin must be given for signal loss across the system and cabling, parasitic loadings, timing, network imbalances, ground offsets, and signal integrity; thus, a practical maximum number of nodes is often lower. Bus length can also be extended beyond 40 meters by careful system design and data rate tradeoffs. For example, CANopen network design guidelines allow the network to be up to 1km with changes in the termination resistance, cabling, less than 64 nodes and significantly lowered data rate.

This flexibility in CAN network design is one of the key strengths of the various extensions and additional standards that have been built on the original ISO 11898-2 CAN standard. However, when using this flexibility the CAN network system designer must take the responsibility of good network design to develop robust network operation.

See the application note [Controller Area Network Physical layer requirements](#). The document discusses in detail all system design physical layer parameters.

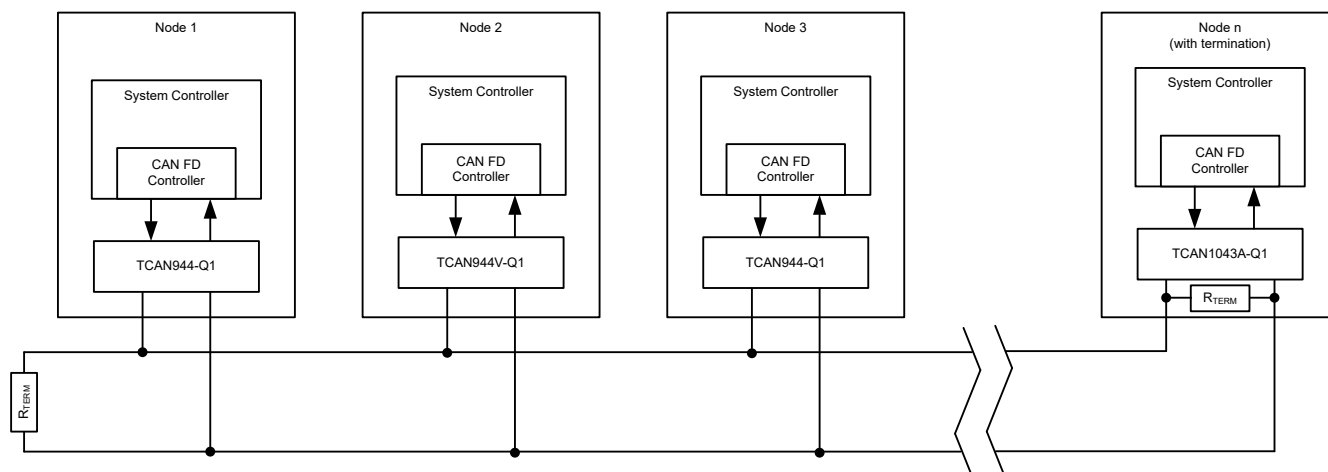


Figure 9-3. Typical CAN Bus

9.2.3 Application Curve

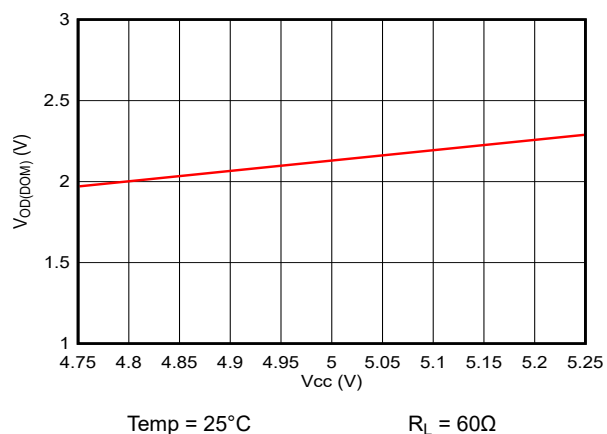


Figure 9-4. $V_{OD(DOM)}$ vs V_{CC}

9.3 System Examples

The TCAN944V-Q1 transceiver is typically used in applications with a host controller or FPGA that includes the link layer portion of the CAN protocol. A 3.3V application is shown in [Figure 9-5](#). The bus termination is shown for illustrative purposes.

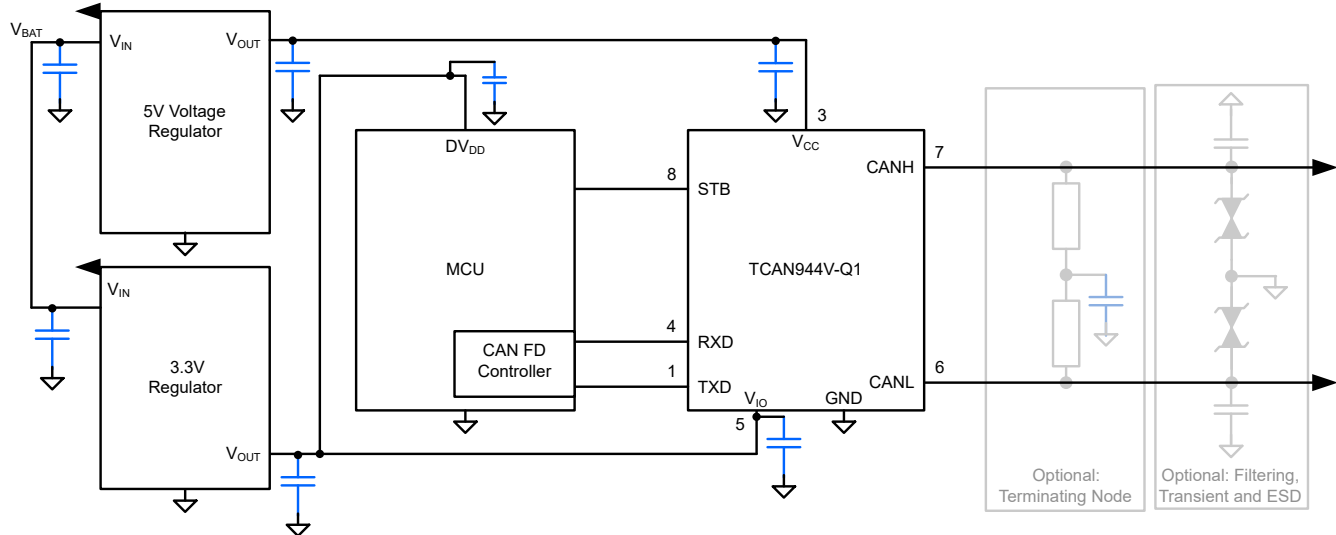


Figure 9-5. Typical Transceiver Application Using 3.3V IO Connections

9.4 Power Supply Recommendations

The TCAN944-Q1 transceiver is designed to operate with a main V_{CC} input voltage supply range between 4.75V and 5.25V.

The TCAN944V-Q1 implements an IO level shifting supply input, V_{IO} , designed for a range between 2.9V and 5.25V.

Both the V_{CC} and V_{IO} inputs must be well regulated. In addition to the power supply filtering a decoupling capacitance, typically 100nF, can be placed near the CAN transceiver main V_{CC} and V_{IO} supply pins.

9.5 Layout

Robust and reliable CAN node design may require special layout techniques depending on the application and design requirements. Since transient disturbances have high frequency content and a wide bandwidth, high-frequency layout techniques must be applied during PCB design.

9.5.1 Layout Guidelines

- Place the protection and filtering circuitry close to the bus connector, J1, to prevent transients, ESD, and noise from propagating onto the board. This layout example shows an optional transient voltage suppression (TVS) diode, D1, which may be implemented if the system-level requirements exceed the specified rating of the transceiver. This example also shows optional bus filter capacitors C4 and C5.
- Design the bus protection components in the direction of the signal path. Do not force the transient current to divert from the signal path to reach the protection device.
- Decoupling capacitors are placed as close as possible to the supply pins V_{CC} and V_{IO} of transceiver.
- Use at least two vias for supply and ground connections of bypass capacitors and protection devices to minimize trace and via inductance.

Note

High-frequency current follows the path of least impedance and not the path of least resistance.

- This layout example shows how split termination could be implemented on the CAN node. The termination is split into two resistors, R2 and R3, with the center or split tap of the termination connected to ground via capacitor C3. Split termination provides common mode filtering for the bus. See [Section 9.2.1.1](#), [Section 8.3.4](#), and [Equation 2](#) for information on termination concepts and power ratings needed for the termination resistor(s).

9.5.2 Layout Example

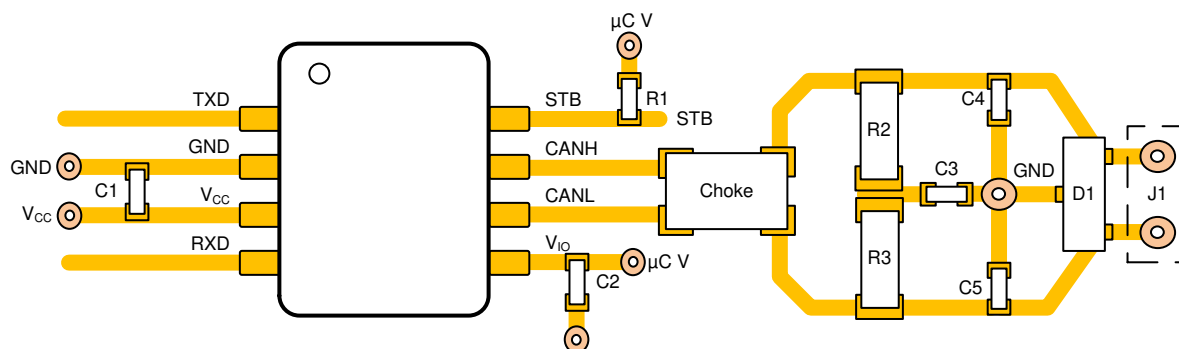


Figure 9-6. Layout Example

10 Device and Documentation Support

10.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

10.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

11 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
September 2026	*	Initial Release

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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